Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

Please cancel claims 1-22.

23. (New) A method for manufacturing a semiconductor wafer comprising steps of, at least: obtaining information of a device manufacturing process as for a device manufacturing process; analyzing the information of the device manufacturing process and selecting a wafer manufacturing process which can manufacture a semiconductor wafer having wafer characteristics corresponding to the information of the device manufacturing process; and manufacturing a semiconductor wafer according to the selected wafer manufacturing process.

24. (New) The method for manufacturing a semiconductor wafer according to Claim 23, wherein the information of the device manufacturing process includes information as for an apparatus used in the device manufacturing process.

25. (New) The method for manufacturing a semiconductor wafer according to Claim 24, wherein the information as for the apparatus used in the device manufacturing process includes information as for a wafer chuck of the apparatus.

26. (New) The method for manufacturing a semiconductor wafer according to Claim 23, wherein the information of the device manufacturing process includes information expressed with an ABC parameter which consists of a maximum value A, a minimum value B and a standard deviation C of displacement of a reference line in a wafer surface and the wafer surface.

27. (New) The method for manufacturing a semiconductor wafer according to Claim 25, wherein the information of the device manufacturing process includes information expressed with an ABC parameter which consists of a maximum value A, a minimum value B and a standard deviation C of displacement of a reference line in a wafer surface and the wafer surface.

28. (New) The method for manufacturing a semiconductor wafer according to Claim 23, wherein the information of the device manufacturing process includes information as for at least one process selected from a lithography process, a heat treatment process, a CMP process, and an etching process.

29. (New) The method for manufacturing a semiconductor wafer according to Claim 27, wherein the information of the device manufacturing process includes information as for at least one process selected from a lithography process, a heat treatment process, a CMP process, and an etching process.

30. (New) The method for manufacturing a semiconductor wafer according to Claim 23 further comprising a step of printing a laser mark corresponding to the information of the device manufacturing process on the semiconductor wafer.

31. (New) The method for manufacturing a semiconductor wafer according to Claim 29 further comprising a step of printing a laser mark corresponding to the information of the device manufacturing process on the semiconductor wafer.

32. (New) A method for receiving an order for manufacture of a semiconductor wafer comprising, at least: a step of connecting a device maker with a customer computer in a wafer maker through a network; a step wherein the customer computer in the wafer maker receives at least information of a device manufacturing process as for a device manufacturing process in the device maker from the device maker through a network; and, a step of analyzing the information of the device manufacturing process and selecting a wafer manufacturing process in which a semiconductor wafer having wafer characteristics corresponding to the information of the device manufacturing can be manufacture.

33. (New) The method for receiving an order for manufacture of a semiconductor wafer according to Claim 32, wherein the information of the device manufacturing process includes information as for an apparatus used in the device manufacturing process in the device maker.

34. (New) The method for receiving an order for manufacture of a semiconductor wafer according to Claim 33, wherein the information as for the apparatus used in the device maker includes information as for a wafer chuck of the apparatus.

35. (New) The method for receiving an order for manufacture of a semiconductor wafer according to Claim 32, wherein the information of the device manufacturing process includes information expressed with an ABC parameter which consists of a maximum value A, a minimum value B and a standard deviation C of displacement between a reference line in a wafer surface and the wafer surface.

36. (New) The method for receiving an order for manufacture of a semiconductor

wafer according to Claim 34, wherein the information of the device manufacturing process includes information expressed with an ABC parameter which consists of a maximum value A, a minimum value B and a standard deviation C of displacement between a reference line in a wafer surface and the wafer surface.

37. (New) The method for receiving an order for manufacture of a semiconductor wafer according to Claim 32, wherein the information of the device manufacturing process includes information as for at least one process selected from a lithography process, a heat treatment process, a CMP process, and an etching process.

38. (New) The method for receiving an order for manufacture of a semiconductor wafer according to Claim 36, wherein the information of the device manufacturing process includes information as for at least one process selected from a lithography process, a heat treatment process, a CMP process, and an etching process.

39. (New) The method for receiving an order for manufacture of a semiconductor wafer according to Claim 32 further comprising a step of returning information of a semiconductor wafer as for a semiconductor wafer to be manufactured in the selected wafer manufacturing process to the device maker.

40. (New) The method for receiving an order for manufacture of a semiconductor wafer according to Claim 38 further comprising a step of returning information of a semiconductor wafer as for a semiconductor wafer to be manufactured in the selected wafer manufacturing process to the device maker.

41. (New) The method for receiving an order for manufacture of a semiconductor wafer according to Claim 39, wherein the information of the semiconductor wafer to be returned includes the ABC parameter of the semiconductor wafer to be manufactured and/or a configuration of a back surface of the semiconductor wafer.

42. (New) The method for receiving an order for manufacture of a semiconductor wafer according to Claim 40, wherein the information of the semiconductor wafer to be returned includes the ABC parameter of the semiconductor wafer to be manufactured and/or a configuration of a back surface of the semiconductor wafer.

43. (New) The method for receiving an order for manufacture of a semiconductor wafer according to Claim 32, wherein analysis of the information of the device manufacturing process and selection of a wafer manufacturing process are performed using the ABC parameter of the semiconductor wafer to be manufactured and/or the configuration of the back surface of the semiconductor wafer.

44. (New) The method for receiving an order for manufacture of a semiconductor wafer according to Claim 42, wherein analysis of the information of the device manufacturing process and selection of a wafer manufacturing process are performed using the ABC parameter of the semiconductor wafer to be manufactured and/or the configuration of the back surface of the semiconductor wafer.

45. (New) A system for receiving an order for manufacture of a semiconductor wafer comprising at least a client terminal in a device maker and a customer computer in a wafer maker, wherein at least information of a device manufacturing process as for a device

manufacturing process in the device maker is inputted into the client terminal by the device maker, and the information of the device manufacturing process is sent through a network, the customer computer receives the sent information of the device manufacturing process, the information of the device manufacturing process is analyzed, and a wafer manufacturing process which can manufacture the semiconductor wafer having wafer characteristics corresponding to the information of the device manufacturing process is selected.

46. (New) The system for receiving an order for manufacture of a semiconductor wafer according to Claim 45, wherein the information of the device manufacturing process includes information as for an apparatus used in the device manufacturing process.

47. (New) The system for receiving an order for manufacture of a semiconductor wafer according to Claim 46, wherein the information as for the apparatus used in the device manufacturing process includes information as for a wafer chuck of the apparatus.

48. (New) The system for receiving an order for manufacture of a semiconductor wafer according to Claim 45, wherein the information of the device manufacturing process includes information expressed with an ABC parameter which consists of a maximum value A, a minimum value B and a standard deviation C of displacement between a reference line in a wafer surface and the wafer surface.

49. (New) The system for receiving an order for manufacture of a semiconductor wafer according to Claim 47, wherein the information of the device manufacturing process includes information expressed with an ABC parameter which consists of a maximum value A, a minimum value B and a standard deviation C of displacement between a reference line in

a wafer surface and the wafer surface.

50. (New) The system for receiving an order for manufacture of a semiconductor wafer according to Claim 45, wherein the information of the device manufacturing process includes information as for at least one process selected from a lithography process, a heat treatment process, a CMP process, and an etching process.

51. (New) The system for receiving an order for manufacture of a semiconductor wafer according to Claim 49, wherein the information of the device manufacturing process includes information as for at least one process selected from a lithography process, a heat treatment process, a CMP process, and an etching process.

52. (New) The system for receiving an order for manufacture of a semiconductor wafer according to Claim 45, wherein the customer computer returns information of a semiconductor wafer as for a semiconductor wafer manufactured by the selected wafer manufacturing process to a client terminal.

53. (New) The system for receiving an order for manufacture of a semiconductor wafer according to Claim 51, wherein the customer computer returns information of a semiconductor wafer as for a semiconductor wafer manufactured by the selected wafer manufacturing process to a client terminal.

54. (New) The system for receiving an order for manufacture of a semiconductor wafer according to Claim 52, wherein the information of the semiconductor wafer to be returned includes the ABC parameter of the semiconductor wafer to be manufactured and/or a

configuration of a back surface of the semiconductor wafer.

55. (New) The system for receiving an order for manufacture of a semiconductor wafer according to Claim 53, wherein the information of the semiconductor wafer to be returned includes the ABC parameter of the semiconductor wafer to be manufactured and/or a configuration of a back surface of the semiconductor wafer.

56. (New) The system for receiving an order for manufacture of a semiconductor wafer according to Claim 45, wherein analysis of the information of the device manufacturing process and selection of a wafer manufacturing process are performed using the ABC parameter of the semiconductor wafer to be manufactured and/or the configuration of the back surface of the semiconductor wafer.

57. (New) The system for receiving an order for manufacture of a semiconductor wafer according to Claim 55, wherein analysis of the information of the device manufacturing process and selection of a wafer manufacturing process are performed using the ABC parameter of the semiconductor wafer to be manufactured and/or the configuration of the back surface of the semiconductor wafer.